Xinghua Diamond

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Diamond Grinding Wheel For Sapphire Wafer Thinning Lapping

Metal bond Diamond Grinding wheel are used for back thinning of the sapphire epitaxial wafer, silicon wafer, gallium arsenide and GaN wafer rough grinding. Welcome to buy diamond grinding wheel for sapphire wafer thinning lapping from us.

Latest Selling Diamond Grinding Wheel For Sapphire Wafer Thinning Lapping Made in China

Diamond grinding wheel for sapphire wafer thinning lapping
Shape: 6A2T
Body: Aluminum
Bond: Metal
Abrasive: Diamond
Usage: For back thinning of the sapphire epitaxial wafer, silicon wafer, gallium arsenide and GaN wafer rough grinding.

The diamond grinding wheel for sapphire wafer thinning lapping is extremely hard, not only has excellent optical and mechanical performance and good thermal conductivity, but also has good wear resistance and good wind erosion resistance. It is an ideal LED substrate material. Usually, a diamond wheel or ultrafine diamond powder is used for the sapphire substrates processing.

In the process of LED substrate thinning, the metal bond diamond wheel which developed by forturetools are best option to grind this hard material, long service life with better surfacing result. If you have further finishing requirement,it should also choose high-quality resin bond diamond grinding wheels in sapphire wafer thinning to ensure a good finish and low surface damage during the grinding process. It is a good foundation for the sapphire lapping and polishing, which can greatly improve the production efficiency and reduce costs.

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